



ALICE

ITS3

Tuesday 13th June 2023

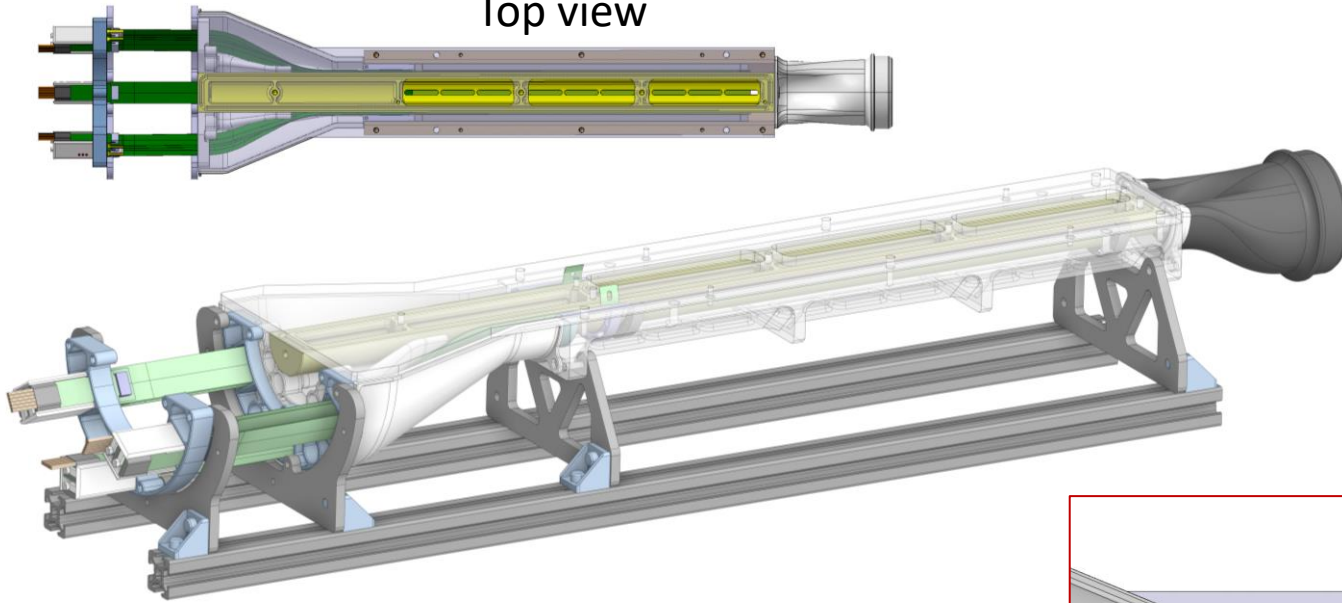
WP5 progress report

WP5 collaboration

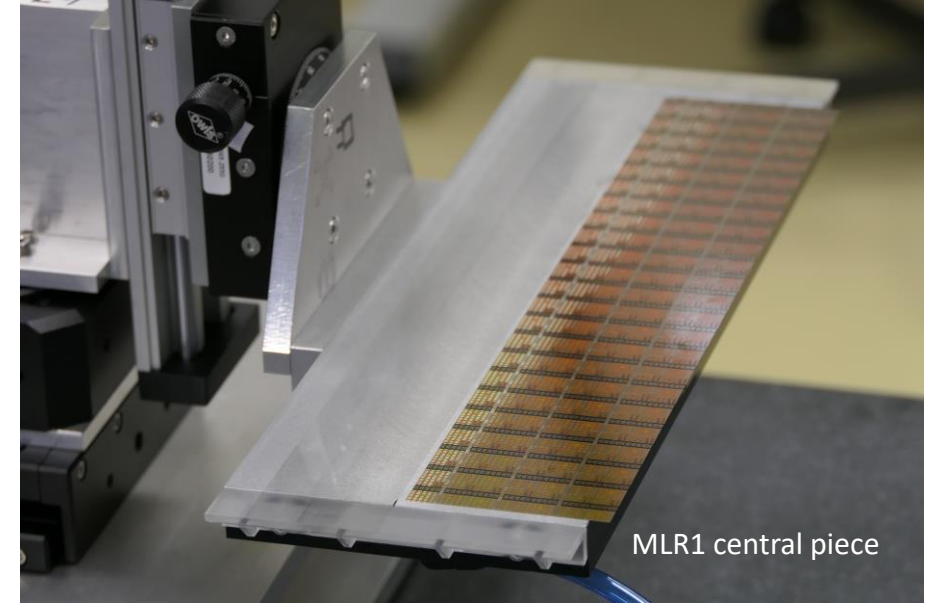
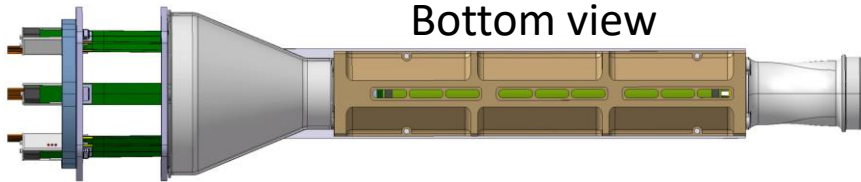
BBM4 bending

- Bending and integration of a real wafer size sensor (L0 size, 50um thin, MLR1 65 nm tech.)
- Wire-bonding integrity under airflow speed 4-8m/s (optical inspect)
- Vibration measurements (identify natural frequencies real sensor)

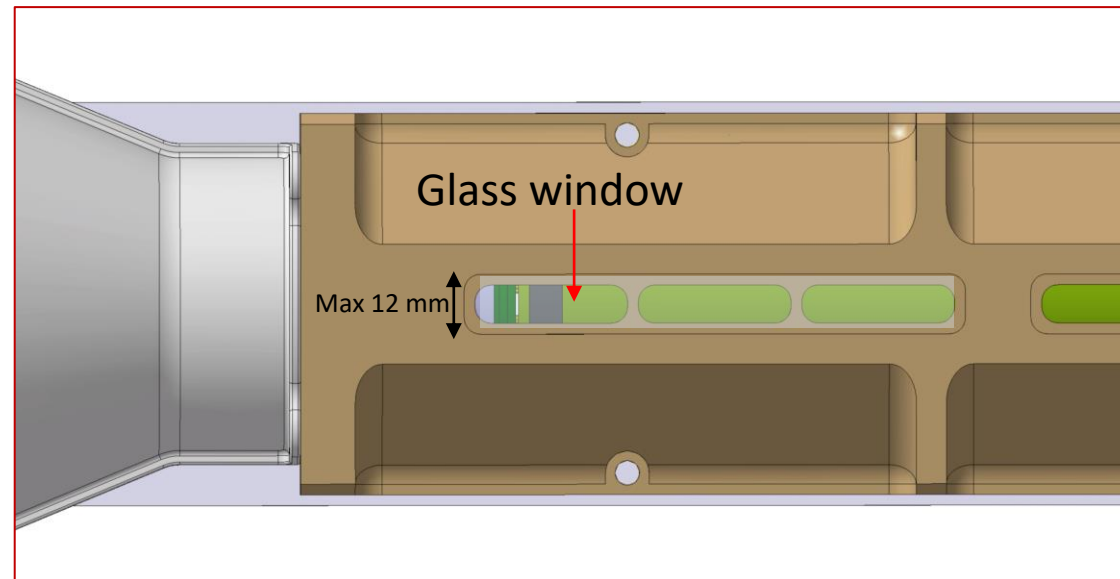
Top view



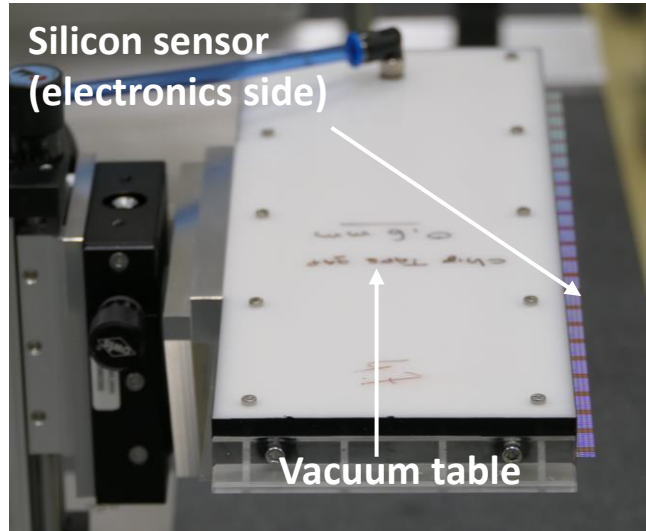
Bottom view



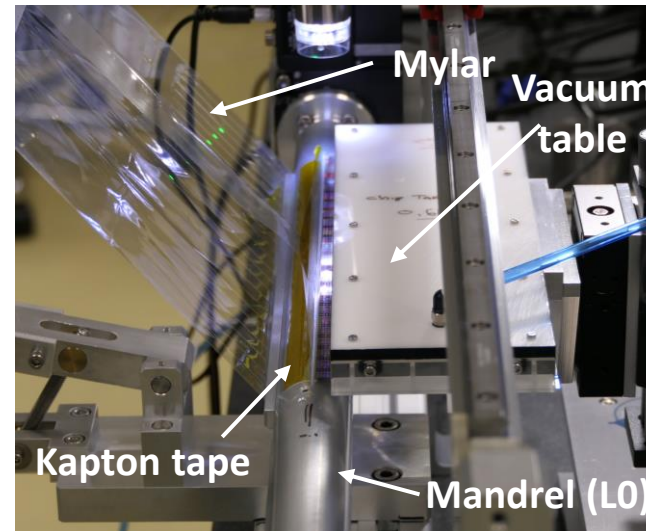
MLR1 central piece



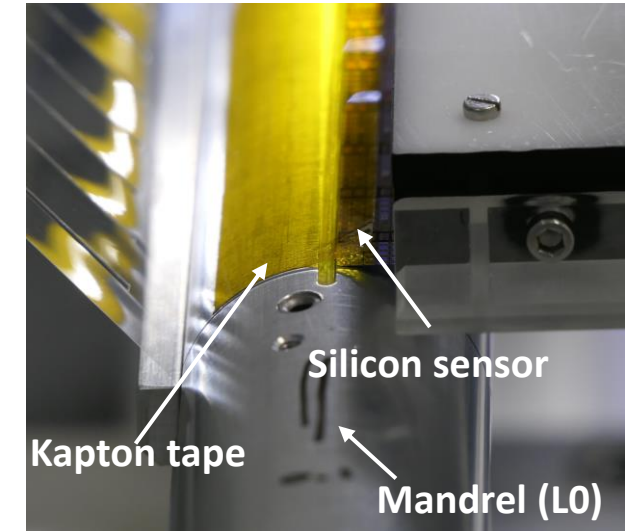
BBM4 bending (11/5/2023 >1 month)



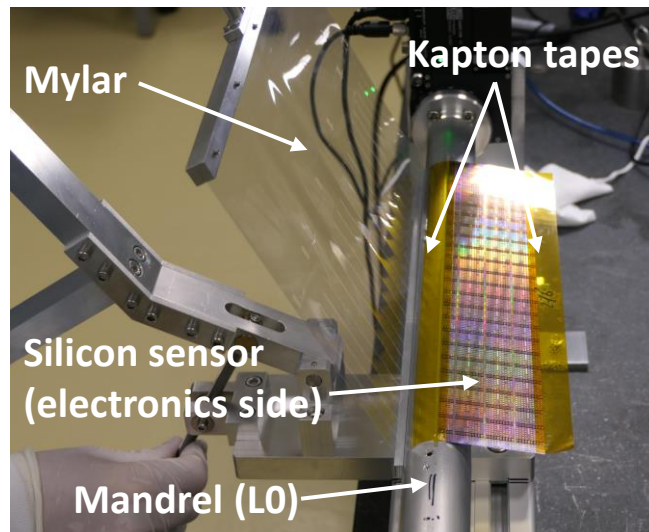
Placement of the sensor in the vacuum table



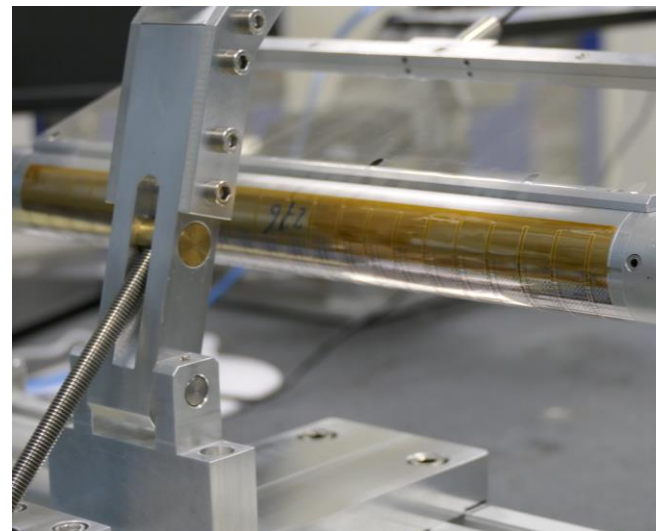
Alignment with the mandrel



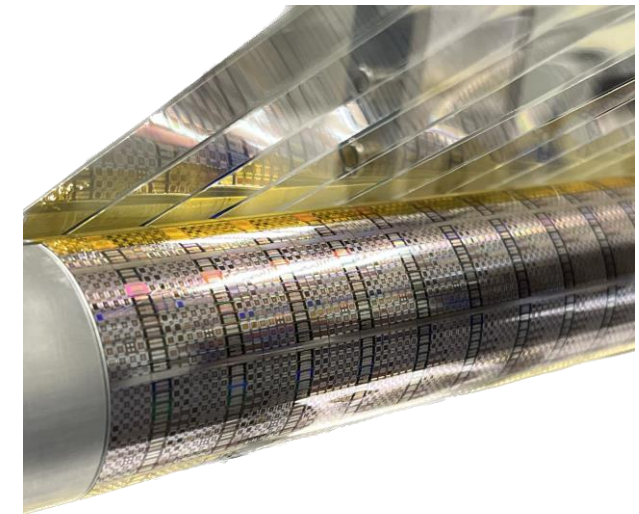
Contact between the kapton tape and the sensor



Start of the bending procedure



End of the bending procedure



Removal of the mylar foil

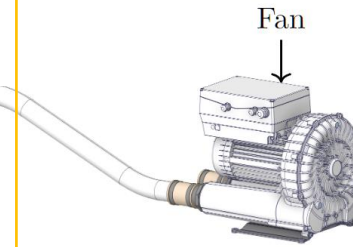


Upgrade of the wind-tunnel ongoing @Philippe, Cedric, Fabio, Pieter

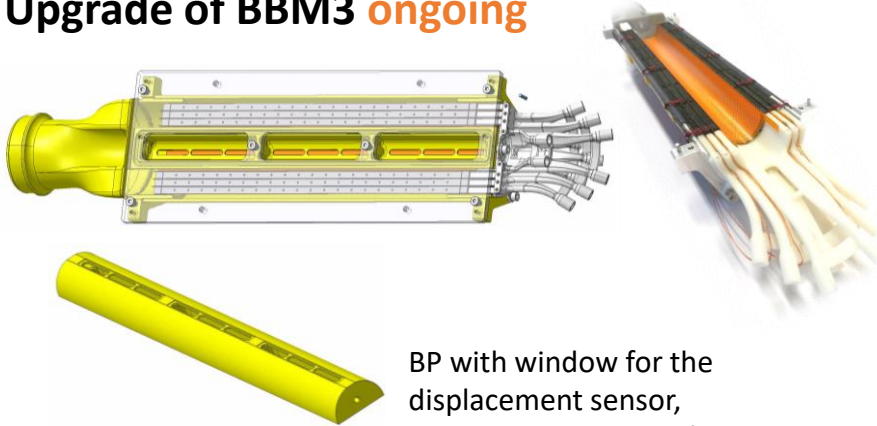


Prototype

Fan outside the lab



Upgrade of BBM3 ongoing



BP with window for the displacement sensor,
For vibration measuring of layer0

Present airflow control system



Upgrade under consideration:
-new chiller (vortex system)

@Pieter, Antoine

BBM4 assembly NEXT

wire-bonding and mechanics gluing
End of June (DSF closed 19/6 – 28/6)

- All assembly parts (almost) ready

Upgrade under consideration:
-new valves, air flow and pressure sensors